



FIG. 2

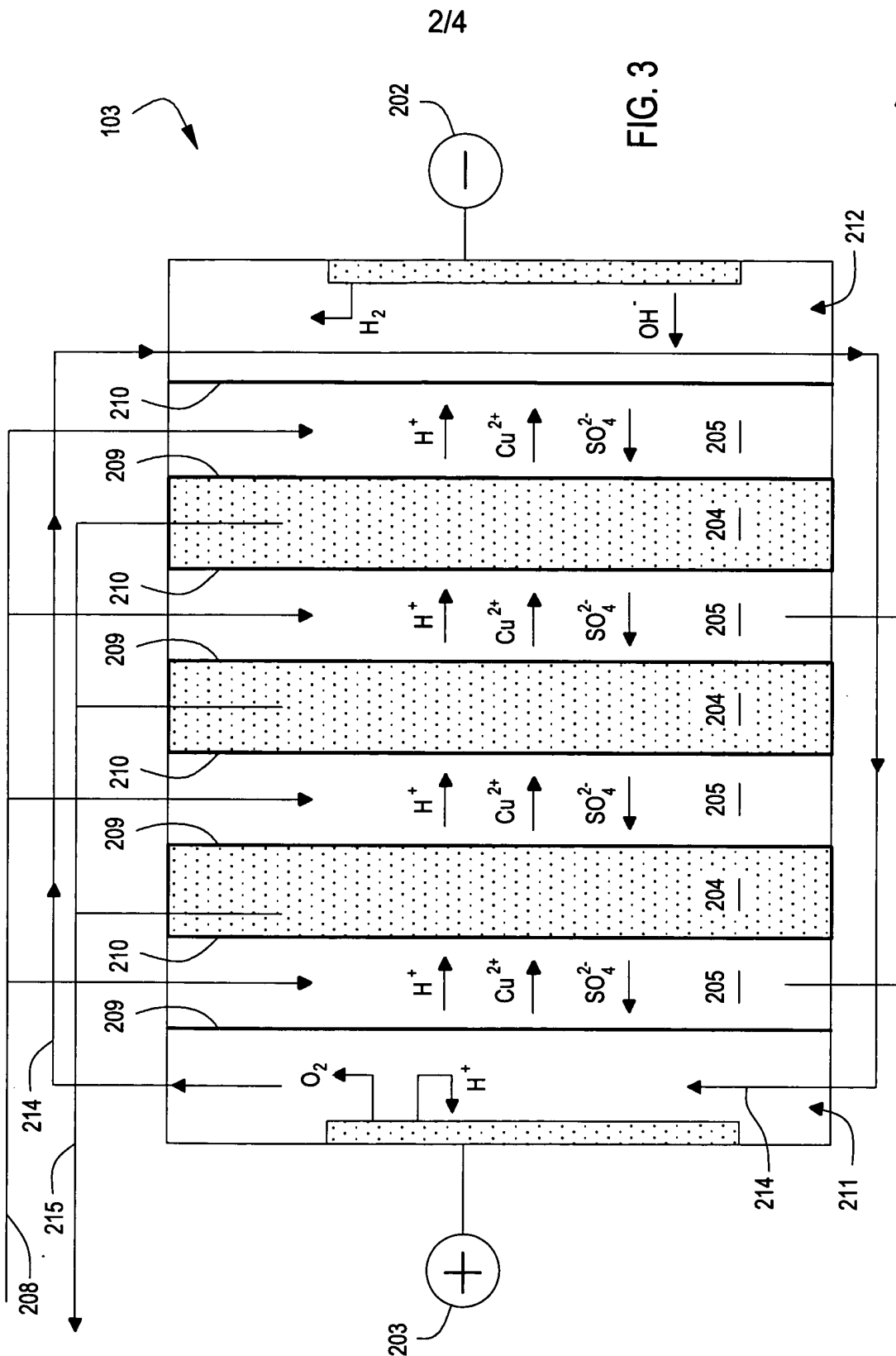


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Apparatus and Method for Removing Contaminants from Semiconductor
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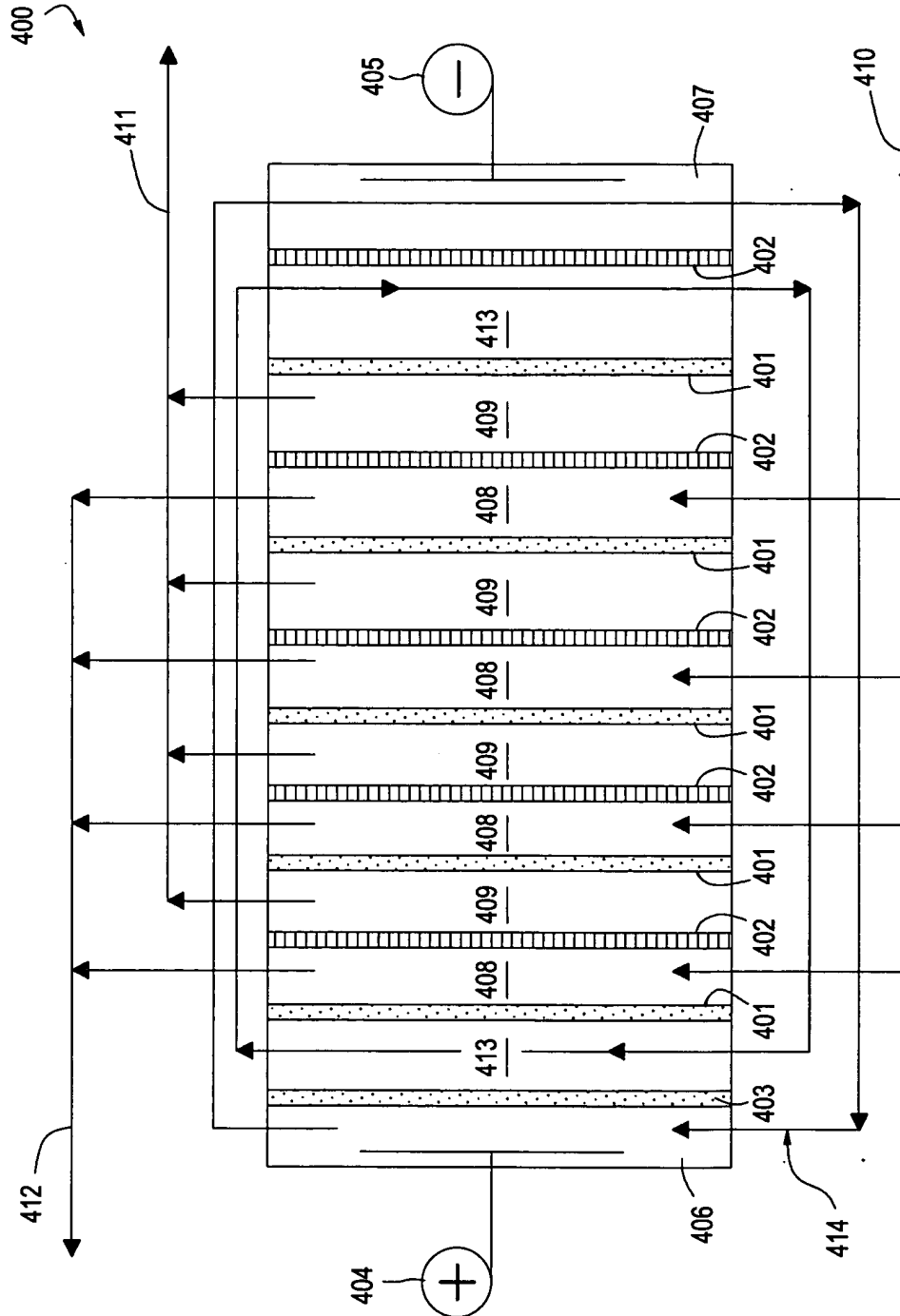


FIG. 4



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FIG. 5

